

6 Physical Layouts

This section contains the board layout and assembly drawings for the EVM.

6.1 Board Layout

Figure 3 shows the top assembly view of the EVM. Figure 4 shows the top etch layer of the EVM. Figure 5 shows the board second etch layer of the EVM. Figure 6 shows the board third etch layer of the EVM. Figure 7 shows the bottom etch layer of the EVM.

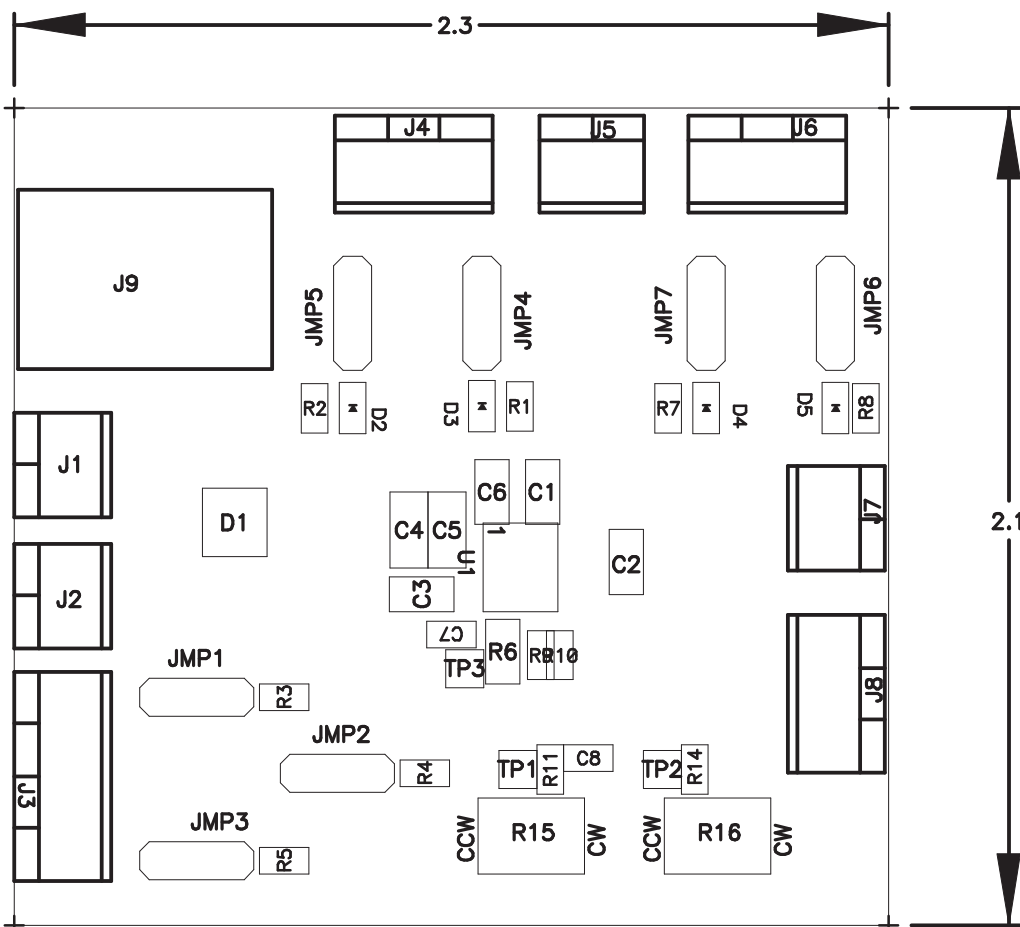


Figure 3. Top Assembly View

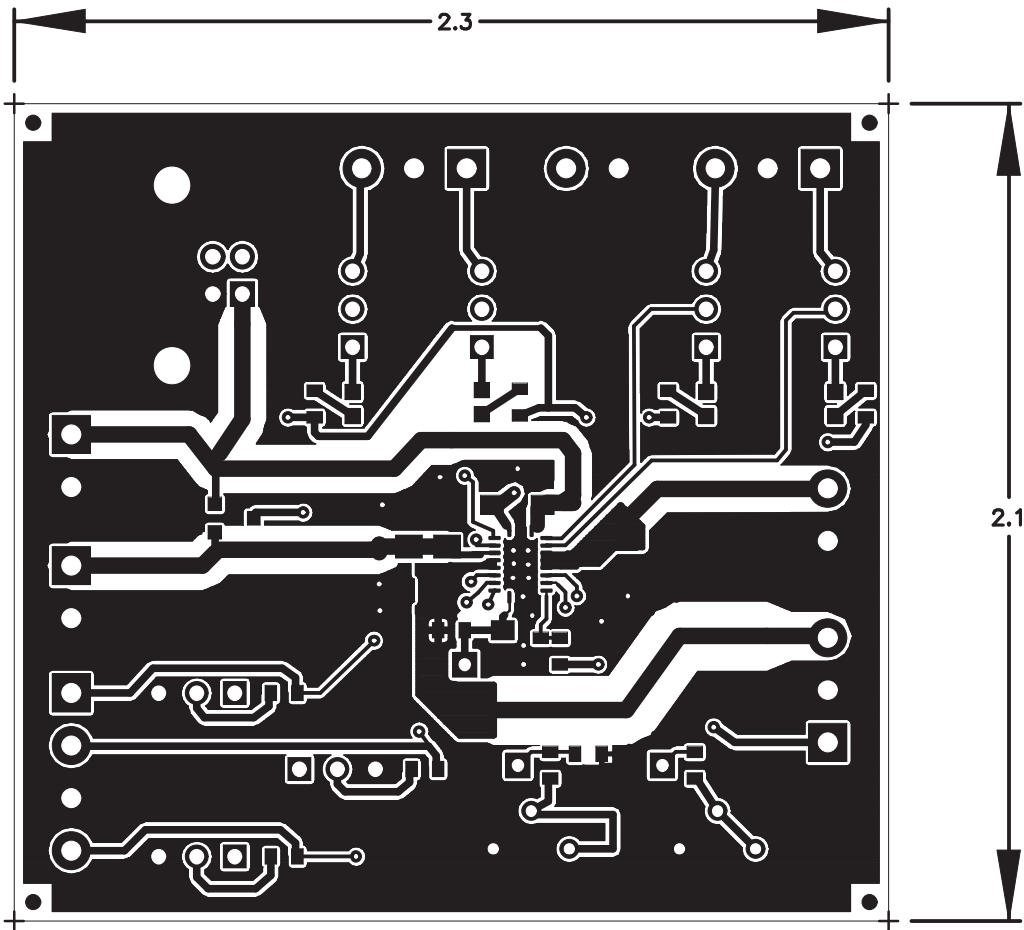


Figure 4. Board Layout – Top Etch Layer

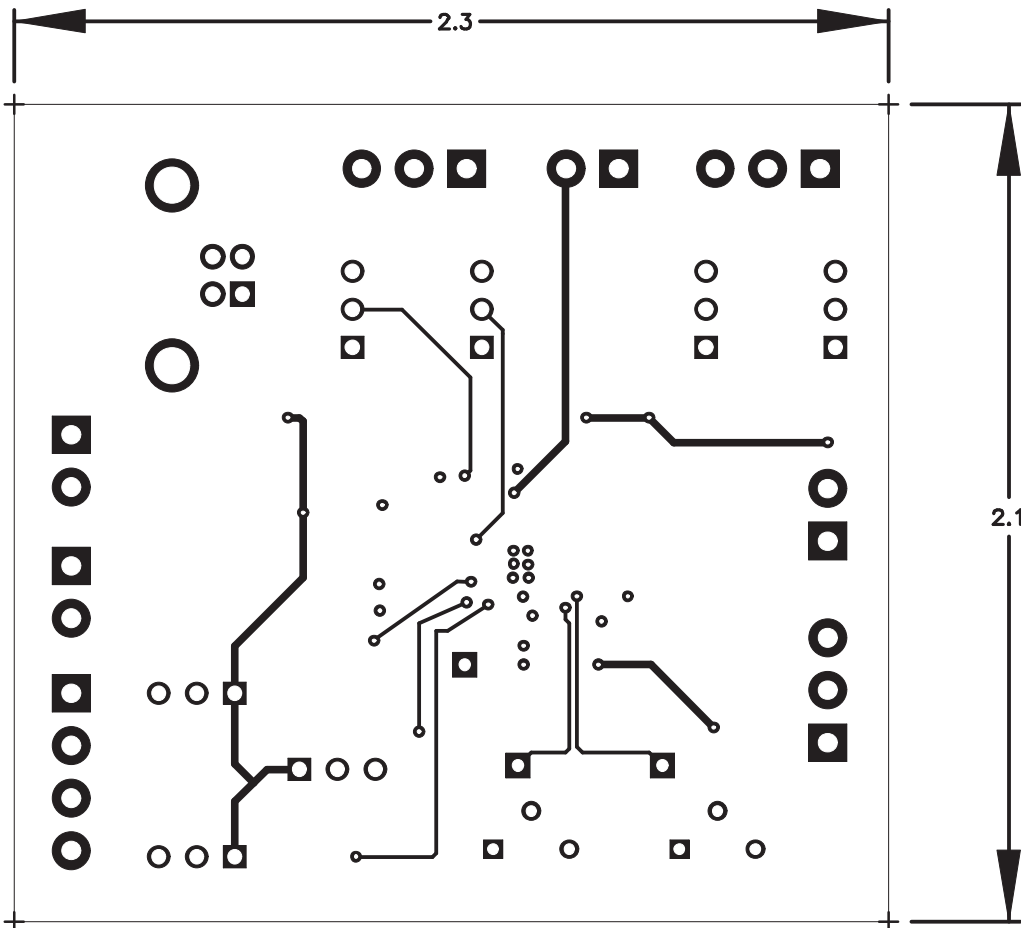


Figure 5. Board Layout – Second Etch Layer

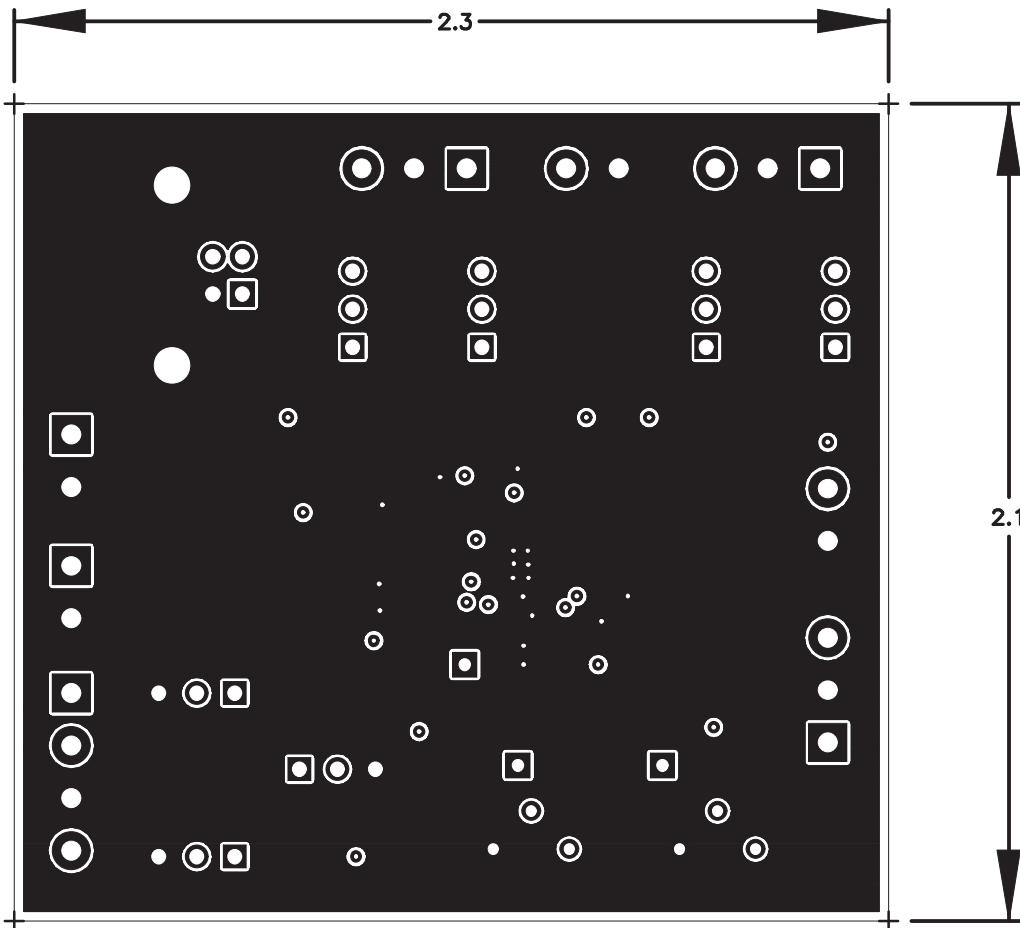


Figure 6. Board Layout – Third Etch Layer

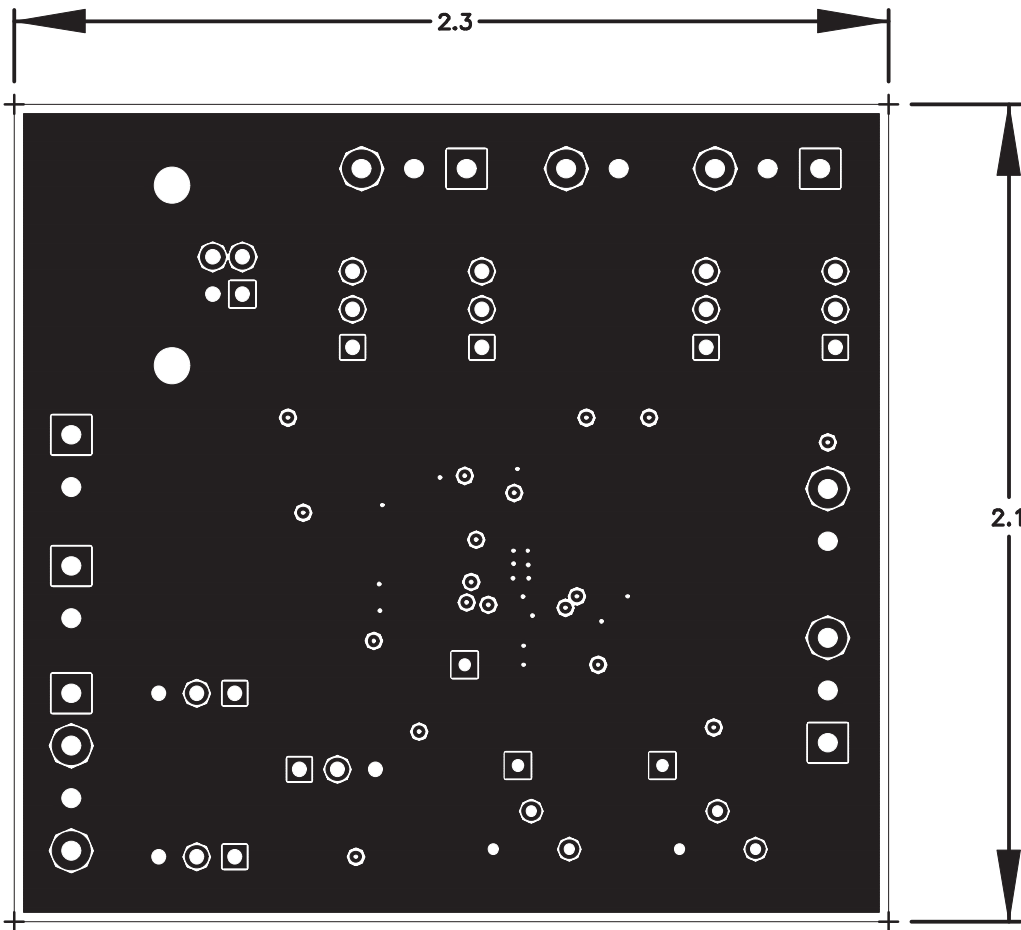


Figure 7. Board Layout – Bottom Etch Layer

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